

OL-NX3P1108

wafer level chip-size package; 4 bumps; 0.96 x 0.96 x 0.55 mm (Backside coating included)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	2-7-2012

Table 1. Package summary

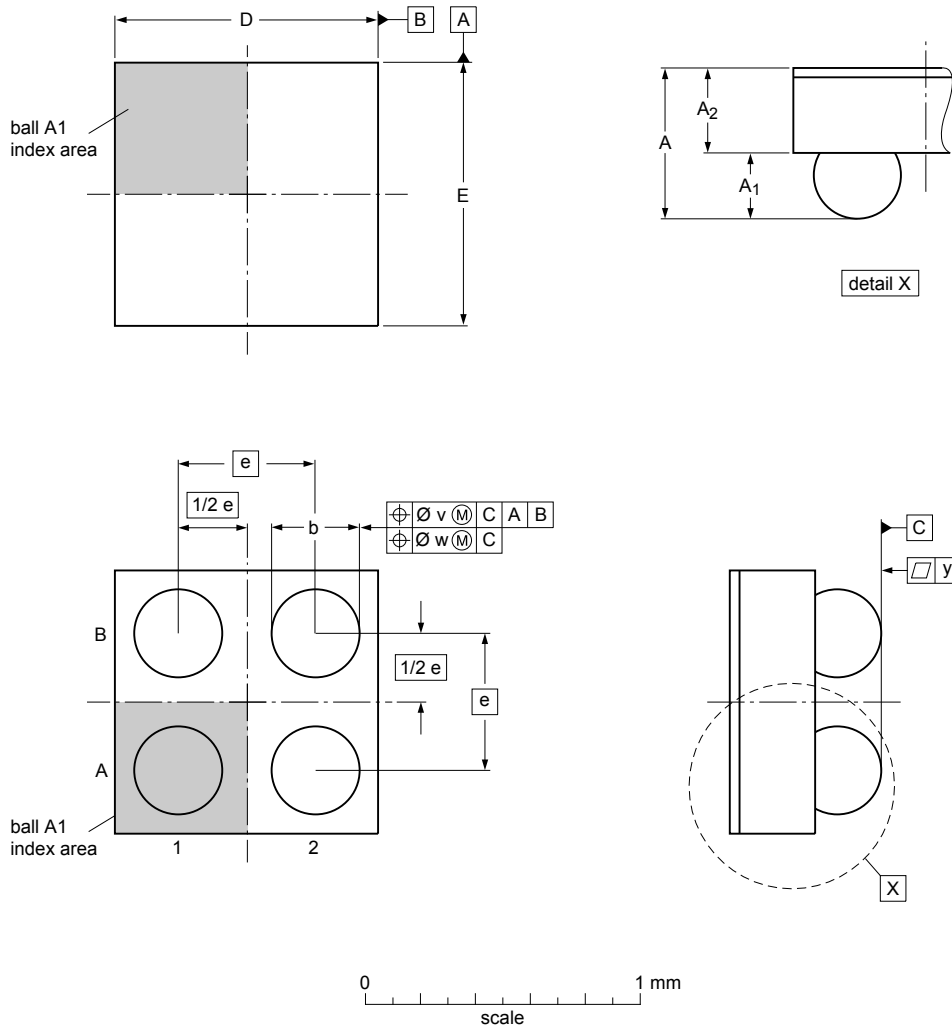
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.94	-	0.96	0.98	mm
E	package width	0.94	-	0.96	0.98	mm
A	seated height	0.51	-	0.55	0.59	mm
A ₂	package height	0.285	-	0.31	0.335	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	4	-	



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2. Package outline

WLCSP4: wafer level chip-size package; 4 bumps; 0.96 x 0.96 x 0.55 mm (Backside coating included) NX3P1107/NX3P1108



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	v	w	y
max	0.59	0.27	0.335	0.35	0.98	0.98				
mm nom	0.55	0.24	0.310	0.32	0.96	0.96	0.5	0.02	0.015	0.03
min	0.51	0.21	0.285	0.29	0.94	0.94				

wlcs4_nx3p1107-8_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
NX3P1107/NX3P1108					-12-06-22- 12-07-02

Fig. 1. Package outline WLCSP (OL-NX3P1108)

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0.96 x 0.55 mm (Backside coating included)

3. Legal information

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